



GaSonics AE 2000LL Isotropic Etcher

6" to 8" Wafer Size

The Aura Loadlock Isotropic Etcher (AE-2000-LL) is a microprocessor-controlled down-stream etcher that etches the front, and optionally, the backside of a wafer.

The AE-2000-LL uses a dual-pumping loadlocked system with a heated split-platen design, wafer transport arms and wafer storage elevators. The AE-2000-LL can be used with wafers of 5-8 inch with only minor hardware modifications.

Features

- Single wafer processing
- Four process gas Mass Flow Controllers
- 5", 6" and 8" wafer capability
- Throughput: 20 to 40wph, depending on process parameters
- Through-the-wall, or Flush-Mount configuration
- Programmable microprocessor
- Automatic wafer loader/unloader
- Main Control Panel
- Regulated platen heat source for process temperature control
- Downstream processing
- Soft-start vacuum system on loadlock chamber
- Ceramic plasma tube (chamber)
- Equipped with hard-wired safety interlocks
- Frontside etching (also capable of backside etching)
- In-line cassette to cassette
- Visual alarms



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Product Specifications

Gas System Features

Flow Rate Stability and Run Uniformity

Description

Mass Flow Controllers are insensitive to changes in downstream pressure.

Gas Flow Repeatability

±0.1% of full scale

Reliable, Leak-free Performance

The Gas Control System is constructed with type 316 SS tubing and components throughout. This ensures corrosion resistant, reliable, leak-free performance.

Operator Control Panel

Versatility

The microprocessor system controls time, temperature, gasses and other parameters in programmed, multi-step process recipes.

Program Control

Unlimited Variability

Program controls ensure no limit of process or program combinations.

Malfunction Troubleshooting

System features a Service Mode and performs troubleshooting self-checks in the event a malfunction or out-of-limit condition occurs.

Service & Physical Specifications

Power

Standard Domestic: 208V, three phase, 60Hz, 5-wire (including ground), 30 amp each phase.

Process Gasses

NF₃ (Gas 1): 15-30 psig delivery pressure
CF₄ (Gas 2): 15-30 psig delivery pressure
He (Gas 3): 15-30 psig delivery pressure
O₂ (Gas 4): 15-30 psig delivery pressure
CDA or N₂: (Pneumatics): 80-90 psig delivery press.

Vacuum

165 CFM (Process Chamber)
15 CFM (Loadlock Chamber)

Exhaust

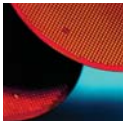
250 CFM

Dimensions

72" (1829mm) high
39.13" (993.90mm) wide
60" (1524mm) deep

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